DSP 700LF (Sn100E)
LEAD FREE
WATER SOLUBLE
SOLDER PASTE

CORPORATE HEADQUARTERS USA: 315 Fairbank St. Addison, IL 60101 ! 630-628-8083! FAX 630-628-6543
EUROPE UK: Unit 9 Apex Ct. Bassendale Rd. Bromborough, Wirral CH62 3RE ! 44 151 334 0888! FAX 44 151 346 1408
ASIA-PACIFIC HEADQUARTERS SINGAPORE: 6 Tuas South St. 5 Singapore 637790 ! 65 6795 7757 ! FAX 65 6795 7767
PHILIPPINES: Phase 1 Qualitek Ave. Mariveles, Bataan Philippines C-2106 ! 6347 935 4119 ! FAX 6347 935 5608
CHINA: 3B/F, YiPa Print Bldg. 351 # JiHua Rd., Buji Shenzhen, China 518112 ! 86 755 28522814 ! FAX 86 755 28522787

Description

Qualitek has developed a unique water soluble flux system designed specifically for Sn100E (Sn/Cu/Co) alloy. It provides the fluxing activity levels that promote thermal stability and prevents thermal degradation when reflowing under air atmosphere.

In addition, DSP 700LF Lead Free solder paste exhibits superior joint strength, excellent wettability, extraordinary print definition and tack life.

Main Features

- Low foaming
- Extended stencil life
- Long tack time
- Excellent wettability

	Specification	**Test Method**
Flux Classification	ORH1	JSTD-004
Copper Mirror	No removal of copper film	IPC-TM-650 2.3.32
Corrosion	Pass	IPC-TM-650 2.6.15
SIR		
JSTD-004	7.88 x 10^{11} ohms	IPC-TM-650 2.6.3.3
Electromigration	Pass	Bellcore GR-78-CORE 13.1.4
Post Reflow Flux Residue	45%	TGA Analysis
Acid Value	113	IPC-TM-650 2.3.13
Metal Loading	88%	IPC-TM-650 2.2.20
Viscosity		
Brookfield (1), kcps	900+/-10% kcps	IPC-TM-650 2.4.34 modified
Malcom (2), poise	2300-2650	IPC-TM-650 2.4.34.3 modified
Thixotropic Index	0.50-0.60	
Slump Test		
25 C, 0.63 vertical/horizontal	No bridges all spacings	IPC-TM-650 2.4.35
150 C, 0.63 vertical/horizontal	No bridges all spacings	IPC-TM-650 2.4.35
25 C, 0.33 vertical/horizontal	0.15 /0.15	IPC-TM-650 2.4.35
150 C, 0.33 vertical/horizontal	0.20/0.20	IPC-TM-650 2.4.35
Solder Ball Test	Pass	IPC-TM-650 2.4.43
Tack		
Initial	95 gm	JIS Z 3284
Tack retention @ 24 hr	120 gm	JIS Z 3284
Tack retention @ 72 hr	117 gm	JIS Z 3284
Stencil Life	4-8 hrs	QIT 3.44.5
Abandon Time	30-60 min	QIT 3.44.6

Physical Properties

Solder Composition

Qualitek Sn100E (Sn99.5/Cu0.5/Co) is designed as a lead-free alternative for Sn/Pb alloys for electronics assembly operations. The Qualitek Sn100E alloy conforms and exceeds the impurity requirements of J-STD-006C and all other relevant international standards.

Typical Analysis														
Sn	**Ag**	**Cu**	**Pb**	**Sb**	**Bi**	**In**	**As**	**Fe**	**Ni**	**Cd**	**Al**	**Zn**	**Au**	**Co**
Bal	0.100 Max	**0.3-0.7**	0.070 Max	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max	0.100 Max

	Sn100E	**Sn63/Pb37**
Melting Point, ℃	228 E	183 E
Hardness, Brinell	9HB	14HB
Coefficient of Thermal Expansion	Pure Sn= 23.5	24.7
Tensile Strength, Mpa	28	44
Density, g/cc	7.40	8.42
Electrical Resistivity , (μohm-cm)	0.123	0.12
Thermal Conductivity, (J/m-s-K)	82	58

Particle Size

Sn100E is available in 3(45-25μm) and 4(38-20μm) J-STD-005 powder distribution. Solder powder distribution is measured utilizing laser diffraction, optical analysis and sieve analysis. Careful control of solder powder manufacturing processes ensures the particles' shape are 95% spherical minimum (aspect ratio < 1.5) and that the alloy contains a typical maximum oxide level of 80 ppm.

Metal Loading

Typical metal loading for stencil printing application is **88-89 %.** Compared to typical Sn63/Sn62 solder pastes manufactured with 90% by weight metal loading, DSP 700LF Lead Free provides as much as 10-12% higher metal volume than Sn63/Sn62. This increased in volume of DSP 700LF promotes better wetting and spreading of Sn100E Lead Free alloy.

Printing of Solder Paste

Stencil

Use of chemical etched/electroformed stencil is preferred however DSP 700LF has been used successfully with chemical etch, electroformed, and laser cut stencils.

Squeegee

Blades: Metal (stainless steel) squeegee blades angled from 45-60° give the best print definition. Metal (nickel) squeegee blades angled from 45-60° give the best performance. 90 durometer polyurethane may also be used.

Pressure: Pressure should be adjusted at the point where the paste leaves a relatively clean stencil after each print pass. Typical pressure setting is 0.6-1.5lb per linear inch of blade.

Speed: Normal print speeds are1.0-2.5 (25-50mm) per second. As print speeds increase pressure will need to be increased. Although slower print speeds are desirable, Qualitek solder paste is capable of printing up to 6 inch per second.

Print Definition

DSP 700LF provides excellent print definition characterized by brick-like prints. Good release is seen on 12-9 mil apertures with prints speeds in the range of 1.0-6.0 inch per second (25mm-150mm).

Open & Abandon Time

Tests have proven that DSP 700LF will perform during continuous printing for up to 8 hrs. Field test have shown that an abandon time of at least 1 hr is possible, resulting in a perfect 1st pass print on resumption of printing.

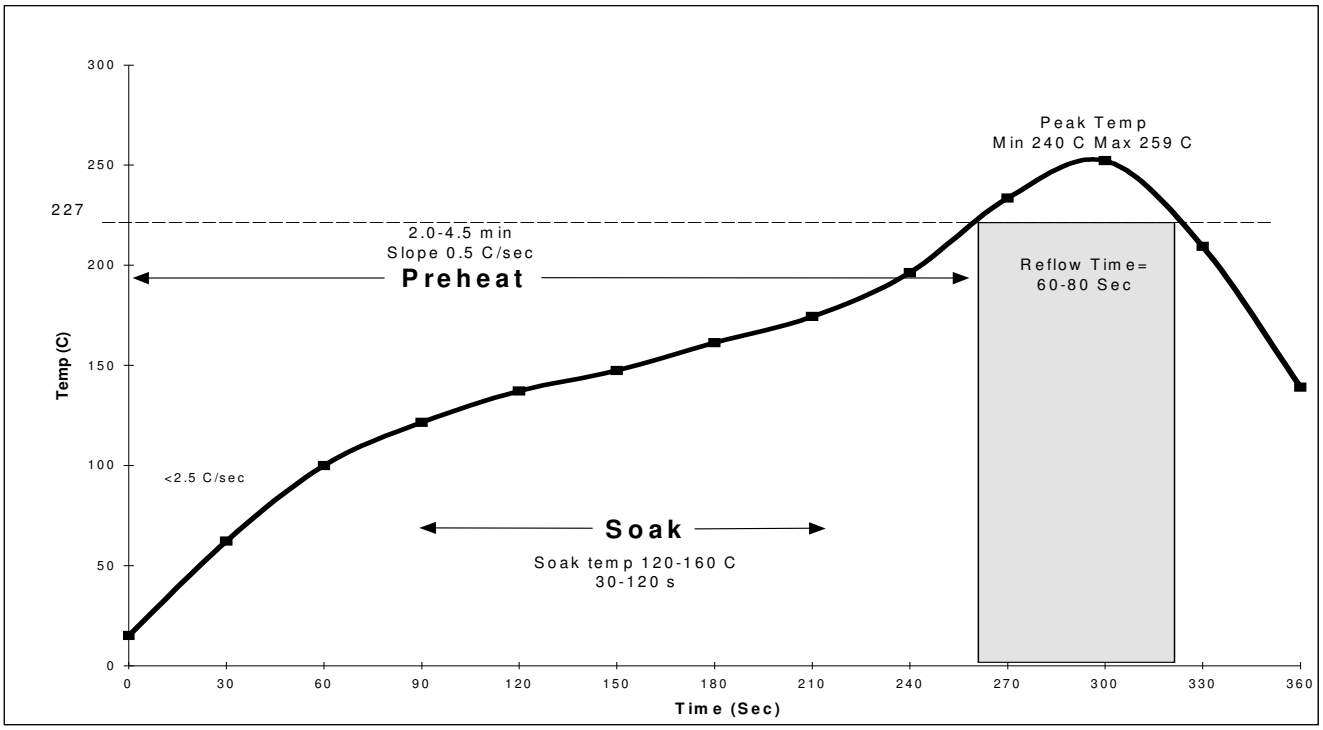
Paste Application

Solder paste should be taken out of the refrigerator at least 3 to 6 hours prior to use. This will give the paste enough time to come to thermal equilibrium with the environment. Also, any fresh jar of solder paste should be gently mixed for at least one minute with a spatula. Be sure not to mix the paste too vigorously, as this will degrade the paste's viscosity characteristics and introduce entrapped air into the paste. The purpose of the mixing is to ensure that the paste is smooth and consistent. If solder paste is supplied in cartridges pre-mixing is not necessary due to the shear action produced from the dispensing.

Reflow

Best results have been acheived when DSP 700LF is reflowed in a ***forced air convection*** oven with a minimum of 8 zones (top & bottom), however, reflow is possible with a 4 zone oven (top & bottom).

The following is a recommended profile for a forced air convection reflow process. The melting temperature of the solder, the heat resistance of the components, and the characteristics of the PCB (i.e. density, thickness, etc.) determine the actual reflow profile.



Preheat Zone*- The preheat zone, is also referred to as the ramp zone, and is used to elevate the temperature of the PCB to the desired soak temperature. In the preheat zone the temperature of the PCB is constantly rising, at a rate that should not exceed 2.5 C/sec. The oven's preheat zone should normally occupy 25-33% of the total heated tunnel length.*

The Soak Zone- *normally occupies 33-50% of the total heated tunnel length exposes the PCB to a relatively steady temperature that will allow the components of different mass to be uniform in temperature. The soak zone also allows the flux to concentrate and the volatiles to escape from the paste.*

The Reflow Zone- *or spike zone is to elevate the temperature of the PCB assembly from the activation temperature to the recommended peak temperature. The activation temperature is always somewhat below the melting point of the alloy, while the peak temperature is always above the melting point.*

Flux Residues & Cleaning

DSP 700LF is a no clean formulation therefore the residues do not need to be removed for typical applications. If residue removal is desired, the use of Everkleen 1005 Buffered Saponifier with a 5-15% concentration in hot 60 ℃ (140 ℉) will aid in residue removal.

Storage & Shelf Life

It is recommended that solder paste be stored at a temperature of between 35-50 ℉ (2-10 ℃) to minimize solvent evaporation, flux separation, and chemical activity. If room temperature storage is necessary it should be maintain between 68-77 ℉ (20-25 ℃).

Shelf Life
Unopened Container (35-50℉/2-10℃) 6 months (from DOM)
Unopened Container (68-77℉/20-25℃) 3 months (from DOM)

Working Environment

Solder paste performs best when used in a controlled environment. Maintaining ambient temperature of between 68-77 ℉ (20-25 ℃) at a relative humidity of 40-65% will ensure consistent performance and maximum life of paste.

Cleaning Misprint Boards

If you should have a misprinted board, the paste may be cleaned off manually with alcohol (IPA) or Qualitek stencil cleaner, SK-11. If you have a more elaborate board cleaner, the paste may be easily removed with use of a 5% saponifier solution in hot DI water. Qualitek SK-45 Stencil Cleaner could be used in this process.

Stencil Cleaning

Periodic cleaning of the stencil during production is recommended to prevent any paste from being deposited in unwanted areas of the board. Without stencil cleaning, solder balling will increase. We recommend a periodic dry wipe (every 5 to 10 boards) with an occasional wet wipe (every 15 to 25 boards). When running fine pitch boards, the cleaning may need to become more frequent. The wet wipes should be performed with either alcohol or a stencil cleaner. Qualitek SK-11 stencil cleaner is designed for this purpose. When cleaning the stencil at the end of a job, the cleaning should be more thorough. If you have stencil cleaning equipment, Qualitek SK- 45 Stencil Cleaner is highly recommended for stencil cleaning purposes.

Packaging

6 oz. Jar	250-500 gm
6 oz. Cartridge	500-700 gm
12 oz. Cartridge	1000-1400gm

Disposal

DSP 700LF should be stored in a sealed container and disposed of in accordance with state & local authority requirements.